

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Kun Hyuk Lee	12/18/2006
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Dongbu Electronics Co., Ltd.
<b>Street Address:</b>	891-10 Daechi-dong, Gangnam-gu
<b>City:</b>	Seoul
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	135-280
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	11613076
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)935-8473
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
<b>Phone:</b>	703-673-1141
<b>Email:</b>	dsherr@sherr-patent.com
<b>Correspondent Name:</b>	Daniel H. Sherr
<b>Address Line 1:</b>	620 Herndon Parkway
<b>Address Line 2:</b>	Suite 200
<b>Address Line 4:</b>	Herndon, VIRGINIA 20170
<b>ATTORNEY DOCKET NUMBER:</b>	601-0062
<b>NAME OF SUBMITTER:</b>	Daniel H. Sherr
<b>Total Attachments: 3</b> source=6010062asn#page1.tif source=6010062asn#page2.tif source=6010062asn#page3.tif	

OP \$40.00 11613076

Docket No.: 601-0062  
Application No.: 11/613,076  
Filing Date: December 19, 2006

**ASSIGNMENT**

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

1) Kun Hyuk LEE residing at 107-1201, Shindonga Apt., 531, Banghak-dong, Dobong-gu, Seoul, Korea 132-762

who has made certain new and useful inventions, hereby sell, assign and transfer unto

**Dongbu Electronics Co., Ltd.**

having an address at

891-10, Daechi-dong, Gangnam-gu, Seoul, Korea 135-280

its successors and assigns (hereinafter designated "ASSIGNEE" the entire right, title and interest for the United States of American as defined in 35 U.S.C. 100 in the invention entitled

**METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE**

for which an application for a United States Patent was filed on Dec. 19, 2006  
identified as U.S. Patent Serial Number 11/613,076

Docket No.: 601-0062  
Application No.: 11/613,076  
Filing Date: December 19, 2006

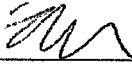
and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and/or that claim priority thereto and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof and/or that claim priority thereto, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, and associated foreign patent applications, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

AND the undersigned hereby grants the firm of SHERR & NOURSE, PLLC the power to insert on this assignment any further identification that may be necessary or desirable in order to comply with the rules of any issuing authority, including the United States Patent and Trademark Office, for recordation of this document.

Docket No.: 601-0062  
Application No.: 11/613,076  
Filing Date: December 19, 2006

SIGNED on the dates indicated aside our signatures:

	INVENTOR	DATE
1)	 Kun Hyuk LEE	December 18 2006